L Number	Hits	Search Text	DB	Time stamp
1	70	laser and ((adhesive near (layer or region or medium or film)) WITH filler) and viscosit$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 08:33
15	167	laser and ((adhesive near (layer or region or medium or film)) WITH viscosit$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 08:11
8	6	laser and ((adhesive near (layer or region or medium or film)) WITH filler WITH viscosit$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 07:33
22	53	laser and ((heat$4 near2 sink) or (cool$5 near (system or member OR assembly))) and (adhesive near (layer or region or medium or film)) and ((active or gain) near (medium or film or layer or region)) and (densit$5 or radiat$5) and thick$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 08:41
29	12	laser and ((heat$4 near2 sink) or (cool$5 near (system or member OR assembly))) and (adhesive near (layer or region or medium or film)) and (((active or gain) near (medium or film or layer or region)) with thick$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 08:21
40	1353	laser and ((adhesive near (layer or region or medium or film)) with (transparent or clear or translucent))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 08:39
47	433	laser and ((adhesive near (layer or region or medium or film)) near2 (transparent or clear or translucent))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 08:41
54	1	laser and ((heat$4 near2 sink) or (cool$5 near (system or member OR assembly))) and ((adhesive near (layer or region or medium or film)) near2 (transparent or clear or translucent)) and ((active or gain) near (medium or film or layer or region))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 08:44
61	4	laser and ((heat$4 near2 sink) or (cool$5 near (system or member OR assembly))) and ((adhesive near (layer or region or medium or film)) WITH (transparent or clear or translucent)) and ((active or gain) near (medium or film or layer or region))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 08:46
-	1002	(solid near state) and active and amplif$5 and cool$4 and thermal$5 and heat$4 and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 16:54
-	391	(solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 16:59
-	251	((solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and 372/$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 17:01

-		259	(solid near state near laser) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 17:01
-		199	((solid near state near laser) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and 372/$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:00
-		154	((solid near state near laser) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and liquid and solid and material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:03
-		244	((solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and liquid and solid and material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:29
-		162	(((solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and liquid and solid and material) and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:24
-		47	((solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 same heat$4) and (liquid with solid same material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:35
-		55	((solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and (liquid with solid same material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:40
-		113	(solid near state) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4 and (liquid same solid same material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:44
-		84	((solid near state) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4 and (liquid same solid same material)) and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:17
-		1	((solid near state with plate) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4 and (liquid same solid same material)) and volum$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:23
-		8	(((solid near state) with plate) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4 and (liquid AND solid AND material)) and volum$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:26
-		20	((solid near state) with plate) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:33

-	20	(((solid near state) SAME plate) and semiconductor and active and laser and amplif\$5 and cool\$4 and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:36
-	1	(((solid near state) with (body or member or system)) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and (cool\$4 near2 (body or member or system)) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:45
-	2	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and (cool\$4 near2 (body or member or system)) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:50
-	1	(((solid near state) with (body or member or system)) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and (cool\$4 near2 (body or member or system)) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:54
-	1	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and cool\$5 and (thermal\$5 near2 (body or member or system)) and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:58
-	0	(((solid near state) with (body or member or system)) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and cool\$5 and (thermal\$5 near2 (body or member or system)) and heat\$4 and (liquid AND solid AND material)) and volum\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:02
-	1	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and cool\$5 and (thermal\$5 near2 (body or member or system)) and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:06
-	95	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif\$5) and (cool\$5) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:18
-	2	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and (cool\$5 near2 (body or member or system)) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:18
-	8	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif\$5) and (cool\$5 near2 (body or member or system)) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:18
-	22	(solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif\$5) and (cool\$5 near2 (body or member or system)) and heat\$4 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:27
-	20	(solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif\$5) and (cool\$5 near2 (body or member or system)) and heat\$4 and plate and thermal\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:46

-		15	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif$5) and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5) and (mirror or reflect$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:40
-		40	(solid near state) and (active near (layer or region or medium or film)) and laser and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5 and (mirror or reflect$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 07:48
-		8	((solid near state) and (active near (layer or region or medium or film)) and laser and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5 and (mirror or reflect$5)) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 17:05
-		7	(solid near state) and (active near (layer or region or medium or film)) and laser and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5 and (adhesive near (layer or region or medium or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 07:52
-		2	((solid near state) or (solidstate)) and (active near (layer or region or medium or film)) and laser and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5 and (adhesive near (layer or region or medium or film)) and (mirror or reflect$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 08:03
-		7	((solid near state) or (solidstate)) and (active near (layer or region or medium or film)) and laser and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5 and (adhesive near (layer or region or medium or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 08:06
-		40	((solid near state) or (solidstate)) and (active near (layer or region or medium or film)) and laser and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5 and (mirror or reflect$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 08:05
-		18	(active near (layer or region or medium or film)) and laser and (cool$5 near2 (body or member or system)) and heat$4 and thermal$5 and (adhesive near (layer or region or medium or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 08:11
-		14	((active near (layer or region or medium or film)) and laser and (cool$5 near2 (body or member or system)) and heat$4 and thermal$5 and (adhesive near (layer or region or medium or film))) and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 08:09
-		7	(active near (layer or region or medium or film)) and laser and (cool$5 near (body or member or system)) and heat$4 and thermal$5 and (adhesive near (layer or region or medium or film)) and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 09:10
-		46	(active near (layer or region or medium or film)) and laser and heat$4 near2 sink and thermal$5 and (adhesive near (layer or region or medium or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 09:13
-		50	(active near (layer or region or medium or film)) and laser and (heat$4 near2 sink) and (adhesive near (layer or region or medium or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 11:05

-	500	laser and (heat$4 near2 sink) and (adhesive near (layer or region or medium or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 11:24
-	404	(laser and (heat$4 near2 sink) and (adhesive near (layer or region or medium or film))) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 09:58
-	14	(("6344868") or ("6069023") or ("5853622") or ("5644586") or ("5578869") or ("5455462") or ("5329539") or ("5327443") or ("5026748") or ("4990943") or ("4589116") or ("4360965") or ("4126033") or ("4117329")).PN.	USPAT	2002/12/04 11:24
-	7	laser and (heat$4 near2 sink) and (adhesive near (layer or region or medium or film)) and ((("6344868") or ("6069023") or ("5853622") or ("5644586") or ("5578869") or ("5455462") or ("5329539") or ("5327443") or ("5026748") or ("4990943") or ("4589116") or ("4360965") or ("4126033") or ("4117329")).PN.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 14:44
-	606	laser and ((heat$4 near2 sink) or (cool$5 near (system or member))) and (adhesive near (layer or region or medium or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 15:28
-	2	(laser and (heat$4 near2 sink) and (adhesive near (layer or region or medium or film)) and ((("6344868") or ("6069023") or ("5853622") or ("5644586") or ("5578869") or ("5455462") or ("5329539") or ("5327443") or ("5026748") or ("4990943") or ("4589116") or ("4360965") or ("4126033") or ("4117329")).PN.)) and active	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 14:39
-	0	laser and (heat$4 near2 sink) and (adhesive near (layer or region or medium or film)) and ((("6344868") or ("6069023") or ("5853622") or ("5644586") or ("5578869") or ("5455462") or ("5329539") or ("5327443") or ("5026748") or ("4990943") or ("4589116") or ("4360965") or ("4126033") or ("4117329")).PN.) and ((active or gain) near (medium or film or layer or region))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 14:46
-	0	(laser and (heat$4 near2 sink) and (adhesive near (layer or region or medium or film)) and ((active or gain) near (medium or film or layer or region))) and ((("6344868") or ("6069023") or ("5853622") or ("5644586") or ("5578869") or ("5455462") or ("5329539") or ("5327443") or ("5026748") or ("4990943") or ("4589116") or ("4360965") or ("4126033") or ("4117329")).PN.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 15:13
-	57	laser and (heat$4 near2 sink) and (adhesive near (layer or region or medium or film)) and ((active or gain) near (medium or film or layer or region))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 15:28
-	66	laser and ((heat$4 near2 sink) or (cool$5 near (system or member OR assembly))) and (adhesive near (layer or region or medium or film)) and ((active or gain) near (medium or film or layer or region))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 11:18
-	8	laser and (((heat$4 near2 sink) or (cool$5 near (system or member OR assembly))) same (adhesive near (layer or region or medium or film))) and ((active or gain) near (medium or film or layer or region))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/04 16:04
-	56	laser and ((heat$4 near2 sink) or (cool$5 near (system or member OR assembly))) and (adhesive near (layer or region or medium or film)) and ((active or gain) near (medium or film or layer or region)) and (densit$5 or radiat$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 08:12

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-	33	(laser and ((heat$4 near2 sink) or (cool$5 near (system or member OR assembly))) and (adhesive near (layer or region or medium or film)) and ((active or gain) near (medium or film or layer or region)) and (densit$5 or radiat$5)) and solid and liquid$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 13:20
-	74	laser and ((adhesive near (layer or region or medium or film)) same liquid same solid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 08:12
-	28	laser and ((adhesive near (layer or region or medium or film)) WITH liquid with solid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 14:07
-	200	laser and ((adhesive near (layer or region or medium or film)) WITH filler)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 14:09
-	200	laser and ((adhesive near (layer or region or medium or film)) WITH filler)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 07:26